



**3D GLASS
SOLUTIONS**

October 18, 2016

Press Release

TE Connectivity and 3D Glass Solutions Announce a Joint Collaboration on Development of Electronic Interconnect Devices Using Glass-Based System-in-Package (SiP) Technology

Albuquerque, New Mexico -- 3D Glass Solutions, Inc. (3DGS), a world-class expert on the fabrication of electronic packages and devices using photo-definable glass ceramics, announced today a joint collaboration with TE Connectivity Ltd. (NYSE: TEL), on the development of electronic interconnect devices using glass-based System-in-Package (SiP) technology. This agreement leverages 3DGS' patented APEX® Glass technology and its existing glass-based systems and components with TE Connectivity's exceptional device, design, and packaging technology.

Electronic interconnect devices manufactured by 3DGS using APEX® Glass have significant benefits over printed circuit boards, such as,

- up to 70% reduced chip size
- up to 50% power reduction
- up to 50% increase in wireless bandwidth
- wider band applications ranging from DC to 100GHz

“3DGS' photo-definable APEX® Glass provides the highest systems-level integration of passive and active devices for System-in-Package (SiP) products compared to any other packaging technology in the market today”, said Ganesh Bhatt of TE Connectivity.

“We are extremely pleased to be partnering with TE Connectivity on this glass-based SiP application and are confident that this joint collaboration will accelerate the development of new enabling technology”, said Jeb Flemming, Chief Executive Officer of 3DGS. “Our high-value system integration, combined with proven low-cost high-volume manufacturing, will provide significant product differentiation for TE Connectivity.”

ABOUT TE CONNECTIVITY

TE Connectivity (NYSE: TEL) is a \$12 billion global technology leader. Our connectivity and sensor solutions are essential in today's increasingly connected world. We collaborate with engineers to transform their concepts into creations – redefining what's possible using intelligent, efficient and high-performing TE products and solutions proven in harsh environments. Our 72,000 people, including over 7,000 engineers, partner with customers in close to 150 countries across a wide range of industries. We believe EVERY CONNECTION COUNTS – www.TE.com.



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ABOUT 3D GLASS SOLUTIONS

3DGS is a world class expert on the fabrication of electronic packages and devices using photo-definable glass ceramics. We produce a wide variety of OEM glass-based System-on-Chip (SoC) and System-in-Package (SiP) devices using our patented APEX® Glass technology for applications such as telecommunication devices, MEMS sensors, Internet infrastructure components, integrated photonic components, and high-frequency and high-performance RF devices. We have created foundational patent positions related to all photo-sensitive glass-ceramic materials and devices. 3DGS owns the fundamental IP for all four positions (materials, design, device, & manufacturing) related to glass-ceramic devices for the electronics packaging industry. We leverage our unique product solution by providing device manufacturing and systems integration services for a number of standard and custom products. For more information, please visit <http://www.3DGlassSolutions.com> or contact:

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